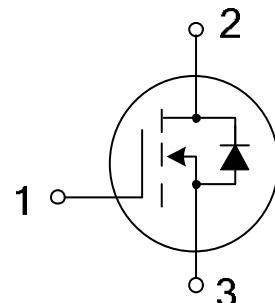


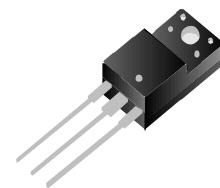
Features

- 800V,5A
- $R_{DS(on)} < 2.7 \Omega @ V_{GS}=10V$ TYP:2.0 Ω
- Low gate charge
- Low Crss
- Fast switching
- Improved dv/dt capability



Applications

- AC-DC power suppliers,
- DC-DC converters
- H-bridge PWM motor drivers



TO-220F

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
5N80F	AP5N80F	TO-220F	-	-	1000

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	800	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current ($T_c = 25^\circ C$)	I_D	5	A
Continuous Drain Current ($T_c = 100^\circ C$)	I_D	3.2	A
Pulsed Source Current ⁽¹⁾	I_{sm}	20	A
Pulsed Drain Current ⁽¹⁾	I_{DM}	20	A
Single Pulsed Avalanche Energy ⁽²⁾	E_{AS}	323	mJ
Power Dissipation	P_D	48	W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	2.6	$^\circ C/W$
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	120	$^\circ C/W$
Junction Temperature	T_J	150	$^\circ C$
Storage Temperature	T_{STG}	-55~+150	$^\circ C$

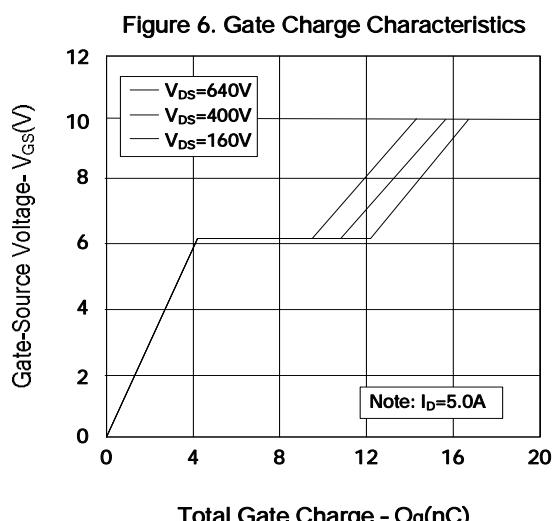
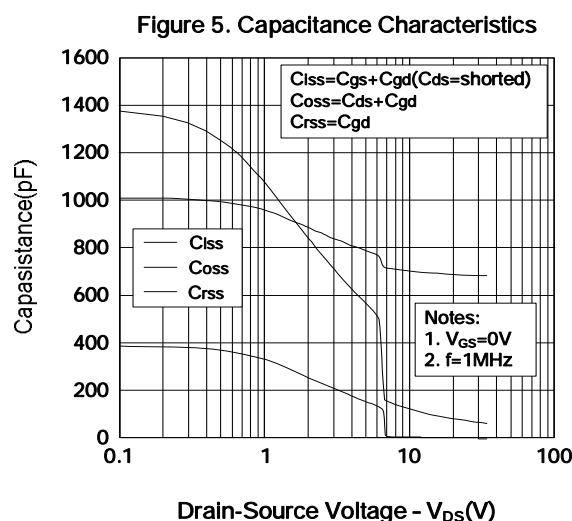
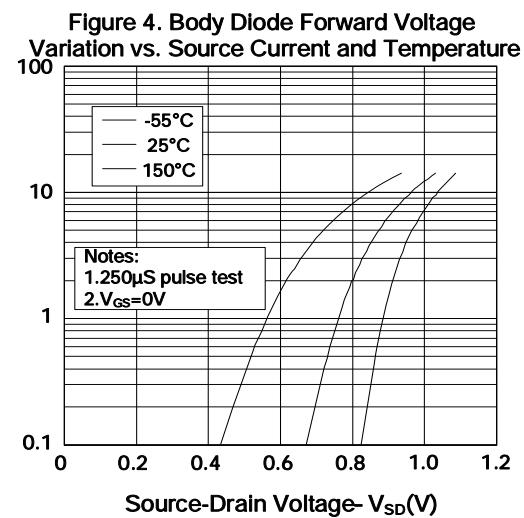
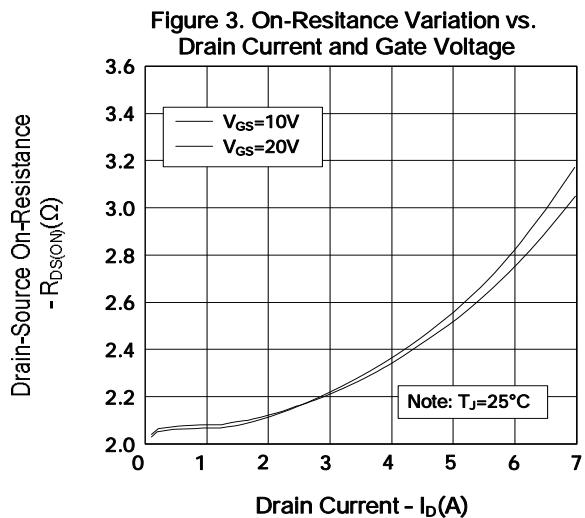
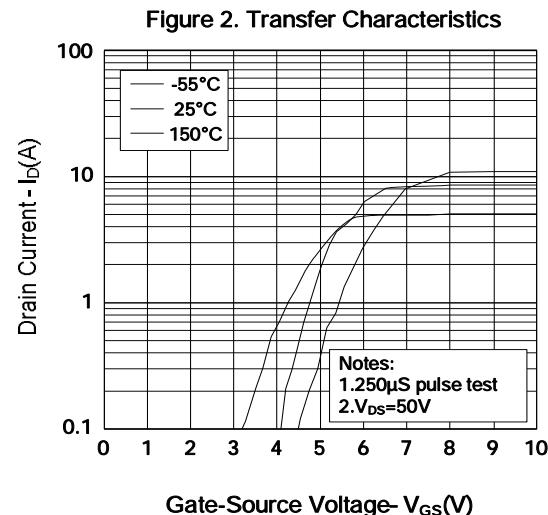
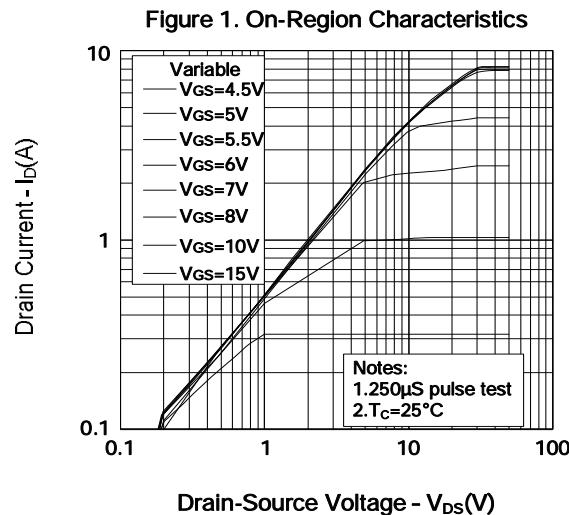
MOSFET ELECTRICAL CHARACTERISTICS($T_a=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	800	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 800V, V_{GS} = 0V, T_J = 25^\circ C$	-	-	1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	± 100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.0	-	4.0	V
Drain-source on-resistance ⁽³⁾	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 2.5A$	-	2.0	2.7	Ω
Dynamic characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$	-	677.1	-	pF
Output Capacitance	C_{oss}		-	71	-	
Reverse Transfer Capacitance	C_{rss}		-	4.0	-	
Switching characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 400V, I_D = 5A, R_G = 25\Omega$	-	11.9	-	ns
Turn-on rise time	t_r		-	23.1	-	
Turn-off delay time	$t_{d(off)}$		-	25.3	-	
Turn-off fall time	t_f		-	23.1	-	
Total Gate Charge	Q_g	$V_{DS} = 640V, I_D = 5A, V_{GS} = 10V$	-	15.16	-	nC
Gate-Source Charge	Q_{gs}		-	4.27	-	
Gate-Drain Charge	Q_{gd}		-	6.78	-	
Source-Drain Diode characteristics						
Diode Forward voltage	V_{SD}	$T_J = 25^\circ C, V_{GS} = 0V, I_S = 5A$	-	-	1.4	V
Diode Forward current	I_S	$T_C = 25^\circ C$	-	-	5.0	A
Body Diode Reverse Recovery Time	trr	$T_J = 25^\circ C, IF = 5A, di/dt = 100A/us$		548.7		ns
Body Diode Reverse Recovery Charge	Qrr	$T_J = 25^\circ C, IF = 5A, di/dt = 100A/us$		2.95		uc

Notes:

1. $L = 30mH, IAS = 4.50A, VDD = 60V, RG = 25\Omega$, starting $TJ = 25^\circ C$;
2. Pulse Test: Pulse width $\leq 300 \mu s$, Duty cycle $\leq 2\%$;
3. Essentially independent of operating temperature.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS (continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

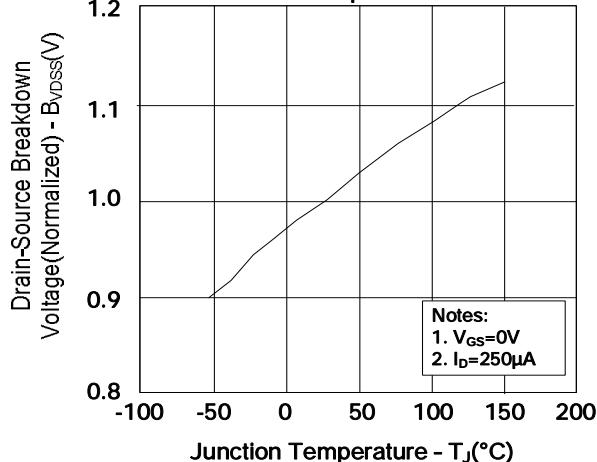


Figure 8. On-resistance Variation vs. Temperature

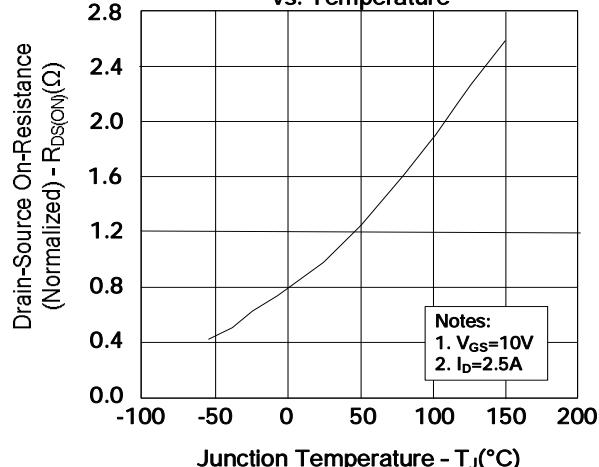


Figure 9-1. Max. Safe Operating Area(SFF5N80)

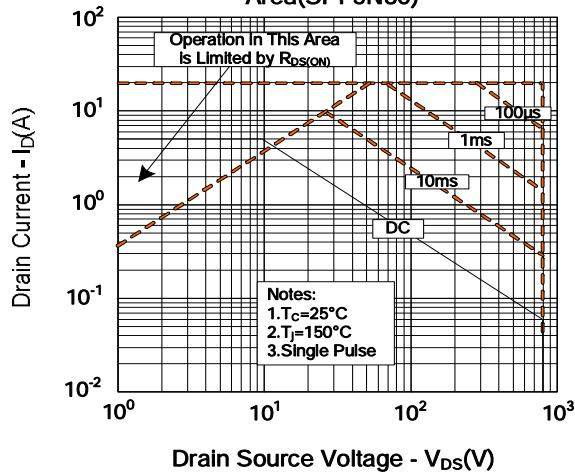


Figure 9-2. Max. Safe Operating Area(SFP5N80)

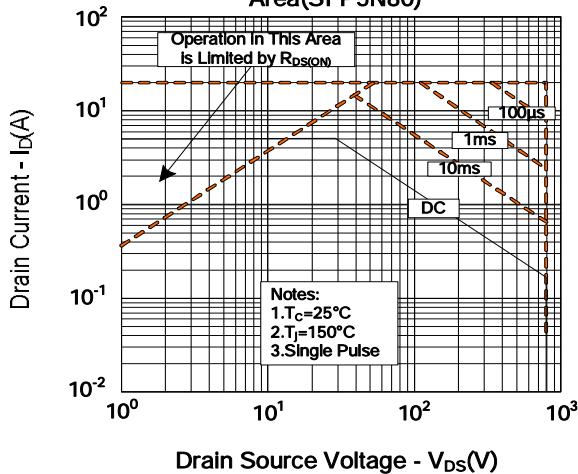
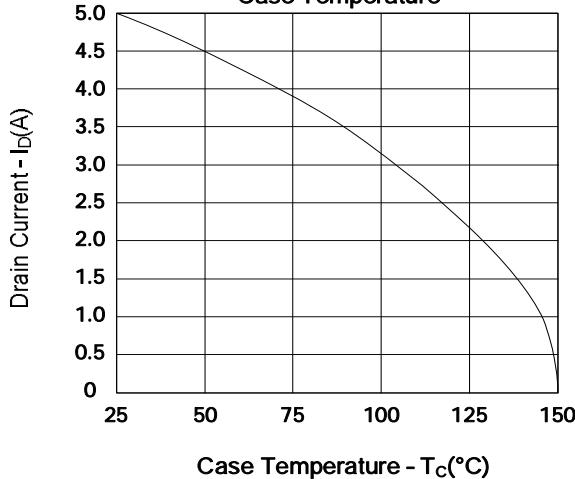
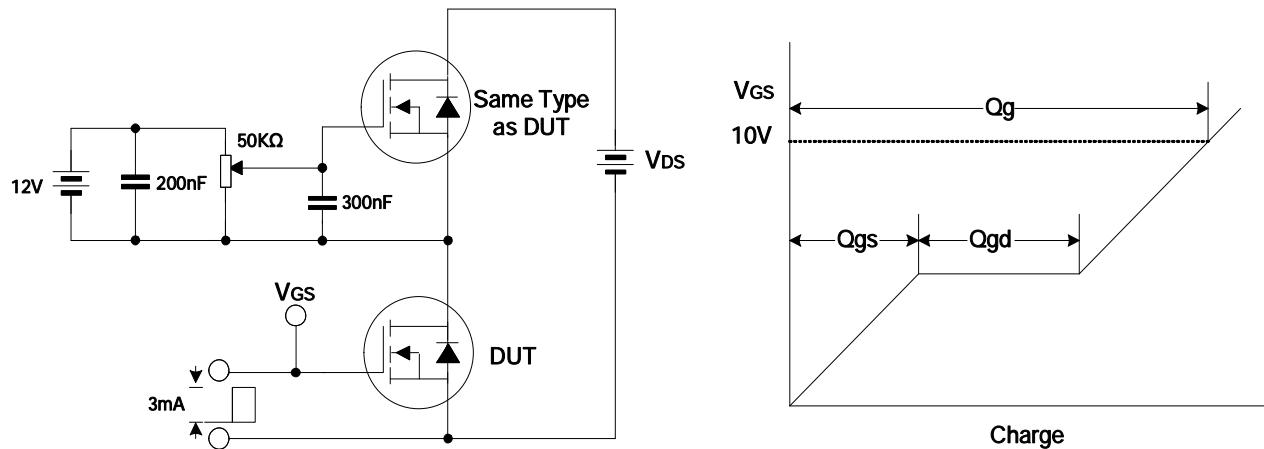


Figure 10. Maximum Drain Current vs. Case Temperature

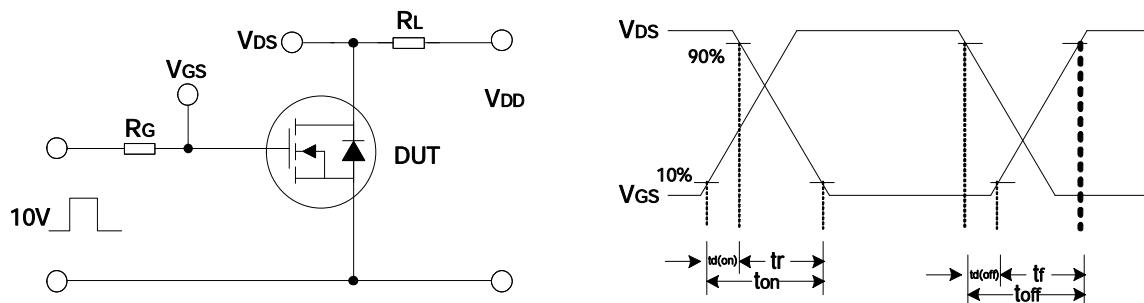


TYPICAL TEST CIRCUIT

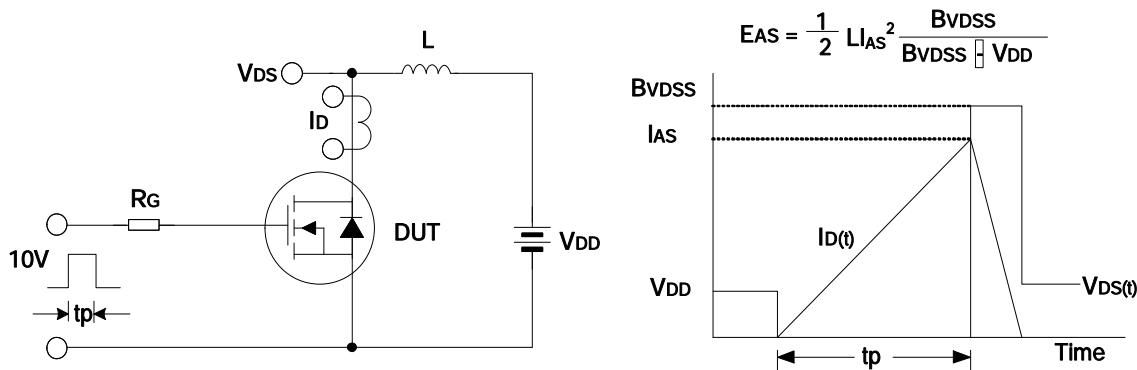
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveform



PACKAGE OUTLINE (continued)

